



Material Content Data Sheet



Sales Product Name		BSS84PW H6327		Issued		19. January 2018		
MA#		MA001231764						
Package		PG-SOT323-3-2		Weight*		6.16 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.03		280	
	noble metal	gold	7440-57-5	0.007	0.11		1084	
	inorganic material	silicon	7440-21-3	0.076	1.23	1.37	12287	13651
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		86	
	non noble metal	titanium	7440-32-6	0.003	0.04		431	
	non noble metal	chromium	7440-47-3	0.008	0.13		1294	
	non noble metal	copper	7440-50-8	2.647	42.95	43.13	429539	431350
wire	non noble metal	copper	7440-50-8	0.005	0.08	0.08	800	800
encapsulation	organic material	carbon black	1333-86-4	0.031	0.50		4975	
	plastics	epoxy resin	-	0.659	10.70		106953	
	inorganic material	silicondioxide	60676-86-0	2.376	38.55	49.75	385527	497455
leadfinish	non noble metal	tin	7440-31-5	0.133	2.15	2.15	21532	21532
plating	noble metal	silver	7440-22-4	0.217	3.52	3.52	35212	35212
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com